# **Quad Buffer with 3-State Outputs**

#### **Features**

- Outputs Source/Sink
- AEC-Q100 Qualified and PPAP Capable (Grade 3)
- These Devices are Pb-Free and are RoHS Compliant

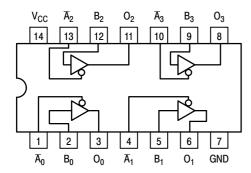


Figure 1. Pinout: 14-Lead Packages Conductors (Top View)

#### **PIN ASSIGNMENT**

PIN	FUNCTION	
$\overline{A}_n$ , $B_n$	Inputs	
On	Outputs	

# **FUNCTION TABLE**

Inp	outs	Output
Ā <sub>n</sub>	B <sub>n</sub>	O <sub>n</sub>
L	٦	L
L	Н	Н
Н	X	Z

NOTE: H = High Voltage Level;

L = Low Voltage Level; Z = High Impedance;

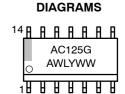
X = Immaterial



# ON Semiconductor®

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**MARKING** 

= Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

G = Pb-Free Package

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
SLV74AC125DR2G	SOIC-14 (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> + 0.5	V
l <sub>in</sub>	DC Input Current, per Pin	±20	mA
l <sub>out</sub>	DC Output Sink/Source Current, per Pin	±50	mA
I <sub>CC</sub>	DC V <sub>CC</sub> or GND Current per Output Pin	±50	mA
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

# **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter			Тур	Max	Unit
V <sub>CC</sub>	Supply Voltage			5.0	6.0	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Ref. to GND)		0	-	V <sub>CC</sub>	V
			-	150	-	
Input Rise and Fall Time (Note 1)	Input Rise and Fall Time (Note 1)  'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	-	40	_	ns/V
	The Series states and the Series and	V <sub>CC</sub> @ 5.5 V	-	25	-	
T <sub>A</sub>	Operating Ambient Temperature Range			25	85	°C
TJ	Junction Temperature			-	125	°C
$\theta_{\sf JA}$	Thermal Resistance, Junction-to-Air (Note 2)			-	101	°C/W
I <sub>OH</sub>	Output Current – HIGH			_	-24	mA
l <sub>OL</sub>	Output Current – LOW		-	_	24	mA

V<sub>in</sub> from 30% to 70% V<sub>CC</sub>; see individual Data Sheets for devices that differ from the typical input rise and fall times.
 The package thermal impedance is calculated in accordance with JESD 51-7.

# **DC CHARACTERISTICS**

		V <sub>CC</sub>	T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C		
Symbol	Parameter	(V)	Тур	(	Guaranteed Limits	Unit	Conditions
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	٧	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	٧	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.46 5.49	2.9 4.4 5.4	2.9 4.4 5.4	٧	I <sub>OUT</sub> = - 50 μA
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $-12 \text{ mA}$ $I_{OH}$ $-24 \text{ mA}$ $-24 \text{ mA}$
V <sub>OL</sub>	Minimum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	٧	I <sub>OUT</sub> = 50 μA
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> 12 mA I <sub>OL</sub> 24 mA 24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	V <sub>I</sub> = V <sub>CC</sub> , GND
I <sub>OZ</sub>	$V_{I}$ (OE) = $V_{IL}$ , $V_{IH}$ $V_{I}$ = $V_{CC}$ , GND $V_{O}$ = $V_{CC}$ , GND	5.5	-	±0.5	±5.0	μΑ	$\begin{aligned} &V_{I}\left(OE\right) = V_{IL},  V_{IH} \\ &V_{I} = V_{CC},  GND \\ &V_{O} = V_{CC},  GND \end{aligned}$
$I_{OLD}$	†Minimum Dynamic	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>	Output Current	5.5	_	_	<b>-75</b>	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	$V_{IN} = V_{CC}$ or GND

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one input loaded at a time.

NOTE:  $I_{IN}$  and  $I_{CC}$  @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V.

## **AC CHARACTERISTICS**

		V <sub>cc</sub> *	T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF		T <sub>A</sub> = - to +8 C <sub>L</sub> = 8		
Symbol	Parameter	(V)	Min	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay Data to Output	3.3 5.0	1.0 1.0	9.0 7.0	1.0 1.0	10 7.5	ns
t <sub>PHL</sub>	Propagation Delay Data to Output	3.3 5.0	1.0 1.0	9.0 7.0	1.0 1.0	10 7.5	ns
t <sub>PZH</sub>	Output Enable Time	3.3 5.0	1.0 1.0	10.5 7.0	1.0 1.0	11 8.0	ns
t <sub>PZL</sub>	Output Enable Time	3.3 5.0	1.0 1.0	10 8.0	1.0 1.0	11 8.5	ns
t <sub>PHZ</sub>	Output Disable Time	3.3 5.0	1.0 1.0	10 9.0	1.0 1.0	10.5 9.5	ns
t <sub>PLZ</sub>	Output Disable Time	3.3 5.0	1.0 1.0	10.5 9.0	1.0 1.0	11.5 9.5	ns

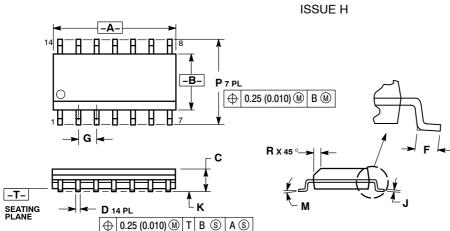
<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm$ 0.5 V.

# **CAPACITANCE**

Symbol	Parameter	Value (Typ)	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	рF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	45	pF	V <sub>CC</sub> = 5.0 V

#### PACKAGE DIMENSIONS

# **SOIC-14**CASE 751A-03



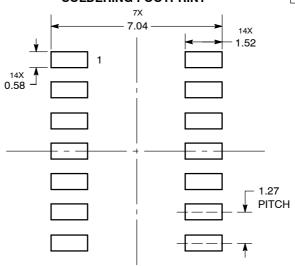
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
- 2. CONTROLLING DIMENSION: MILLIMETER
  3. DIMENSIONS A AND B DO NOT INCLUDE
- MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.

  5. DIMENSION D DOES NOT INCLUDE
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

#### **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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